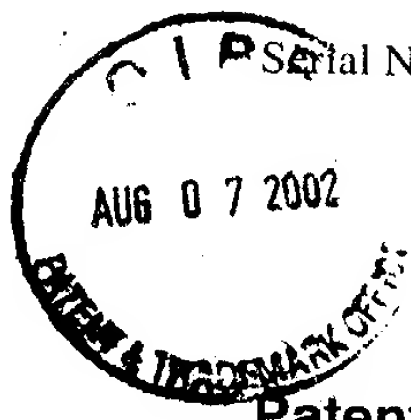


#13/B
8/29/02
Mallist



Serial No. 09/464,811

IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE

Patent Application

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Inventor(s): Shao et al.

Case: 1-10-3

Serial No.: 09/464,811

Filing Date: December 17, 1999

Examiner: Lourdes Cruz

Group Art Unit: 2827

Title: Integration of Low Dielectric Material in Semiconductor Circuit Structures

Mary Carter
Printed name of person mailing paper or fee
Mary Carter
Signature of person mailing paper or fee

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D. C. 20231

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Amendment Under 37 C.F.R. §1.111

SIR:

In response to the office action of April 5, 2002 please amend the application as follows:

IN THE SPECIFICATION

✓ At page 1, change the title to "Integration of Low K Dielectric Material in Semiconductor Circuit Structures."

IN THE CLAIMS

Please amend the claims as follows:

B1

27. A method for fabricating an integrated circuit structure comprising:
forming multiple levels of conductor lines over one another with
some of the levels separated from one another by a layer of first insulative
material;